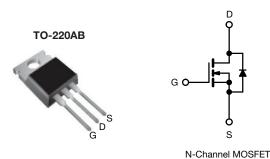
Vishay Siliconix



E Series Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V) at T _J max.	650			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.6		
Q _g max. (nC)	40			
Q _{gs} (nC)	5			
Q _{gd} (nC)	9			
Configuration	Single			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- · Reduced switching and conduction losses
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP7N60E-E3			
Lead (Pb)-free and halogen-free	SiHP7N60E-BE3 ^a			
	SiHP7N60E-GE3			

Note

a. "-BE3" denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
PARAMETER			SYMBOL	LIMIT	UNIT		
Drain-source voltage			V_{DS}	600			
Drain-source voltage	T _C = - 25 °C	$T_C = -25 ^{\circ}\text{C}, I_D = 250 \mu\text{A}$		575	V		
Gate-source voltage			V_{GS}	± 30			
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	I-	7			
	V _{GS} at 10 V	T _C = 100 °C	I _D	5	Α		
Pulsed drain current ^a			I_{DM}	18			
Linear derating factor				0.63	W/°C		
Single pulse avalanche energy ^b			E _{AS}	43	mJ		
Maximum power dissipation			P_{D}	78	W		
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	$T_{J} = 1$	125 °C	dV/dt	70	V/ns		
Reverse diode dV/dt ^d			uv/ut	3	V/11S		
Soldering recommendations (peak temperature) c	For	For 10 s		300	°C		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 13.8 mH, R_g = 25 Ω , I_{AS} = 2.5 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 100 A/µs, starting $T_J = 25$ °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	1.6	G/VV	

PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT			
Static				•					
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		609	-	-	V		
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	Reference to 25 °C, I _D = 1 mA		0.68	-	V/°C		
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	4	٧		
		$V_{GS} = \pm 20 \text{ V}$		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}	,	$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μA		
		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	μΑ		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	V _{DS} = 480 V, V _{GS} = 0 V, T _J = 125 °C		-	10			
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 3.5 A	-	0.5	0.6	Ω		
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 3.5 A		-	1.9	-	S		
Dynamic		*		!		•	•		
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 100 \text{ V},$ f = 1 MHz		-	680	-	pF		
Output capacitance	C _{oss}			-	39	-			
Reverse transfer capacitance	C _{rss}			-	5	-			
Effective output capacitance, energy related ^a	C _{o(er)}	$V_{DS} = 0 \text{ V to } 480 \text{ V}, V_{GS} = 0 \text{ V}$		-	34	-			
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	100	-			
Total gate charge	Qg			-	20	40			
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 3.5 \text{ A}, V_{DS} = 480 \text{ V}$		5	-	nC		
Gate-drain charge	Q _{gd}				9	-			
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 3.5 A,		-	13	26			
Rise time	t _r			-	13	26			
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		24	48	ns -		
Fall time	t _f	1		-	14	28			
Gate input resistance	R_g	f = 1 MHz, open drain		-	1.1	-	Ω		
Drain-Source Body Diode Characteristic	s						•		
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	7			
Pulsed diode forward current	I _{SM}			-	-	18	A		
Diode forward voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 3.5 \text{A}, V_{GS} = 0 \text{V}$		-	-	1.2	V		
Reverse recovery time	t _{rr}	T _J = 25 °C, I _F = I _S = 3.5 A, dl/dt = 100 A/ μ s, V _R = 20 V		-	230	-	ns		
Reverse recovery charge	Q _{rr}			-	1.9	-	μC		
Reverse recovery current	I _{RRM}			_	14	 -	A		

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

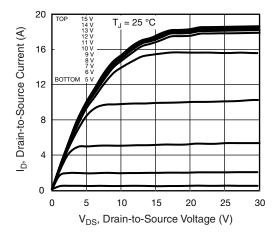


Fig. 1 - Typical Output Characteristics

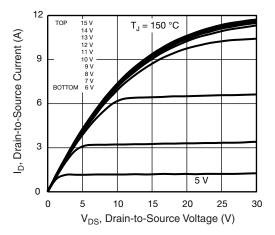


Fig. 2 - Typical Output Characteristics

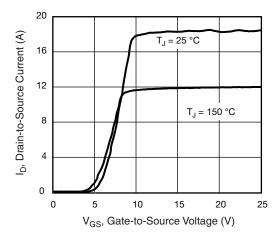


Fig. 3 - Typical Transfer Characteristics

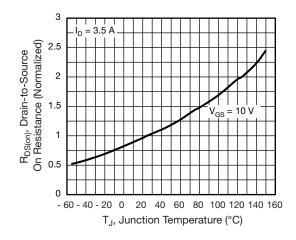


Fig. 4 - Normalized On-Resistance vs. Temperature

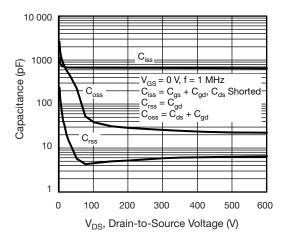


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

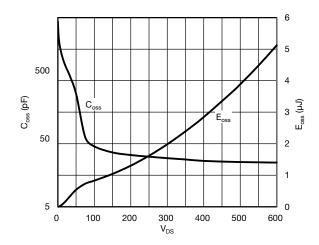


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



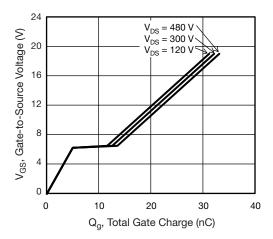


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

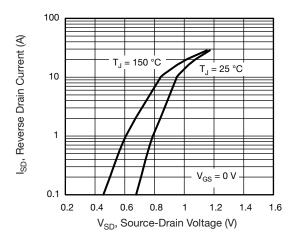


Fig. 8 - Typical Source-Drain Diode Forward Voltage

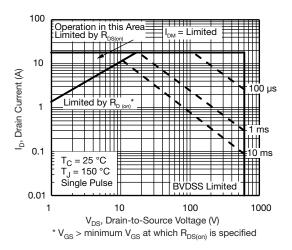


Fig. 9 - Maximum Safe Operating Area

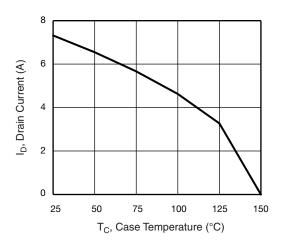


Fig. 10 - Maximum Drain Current vs. Case Temperature

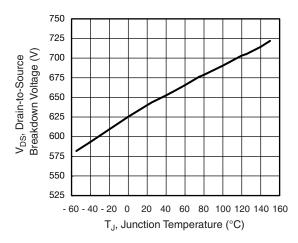


Fig. 11 - Temperature vs. Drain-to-Source Voltage



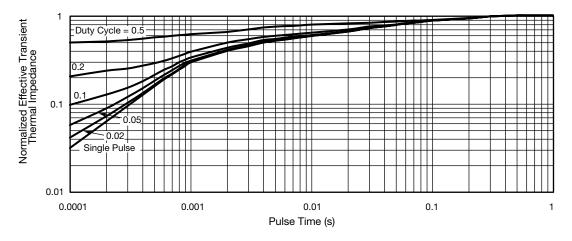


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

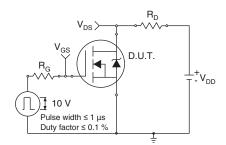


Fig. 13 - Switching Time Test Circuit

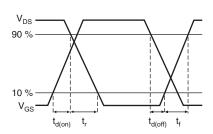


Fig. 14 - Switching Time Waveforms

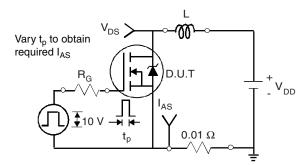


Fig. 15 - Unclamped Inductive Test Circuit

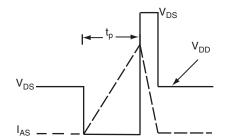


Fig. 16 - Unclamped Inductive Waveforms

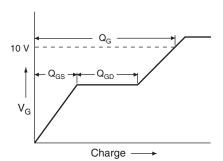


Fig. 17 - Basic Gate Charge Waveform

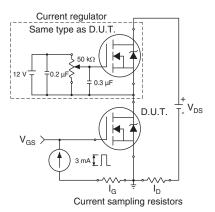
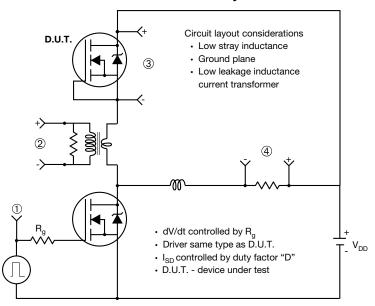


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



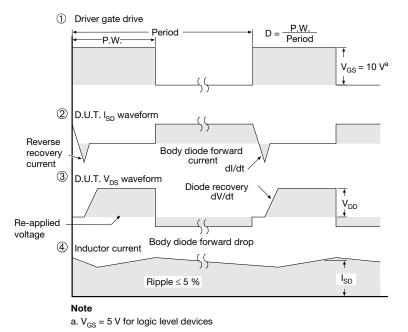


Fig. 19 - For N-Channel

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